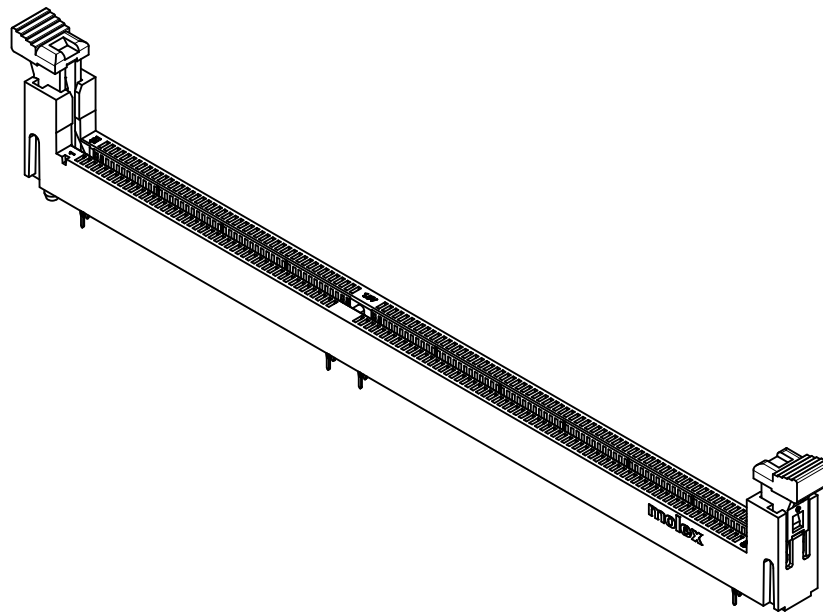
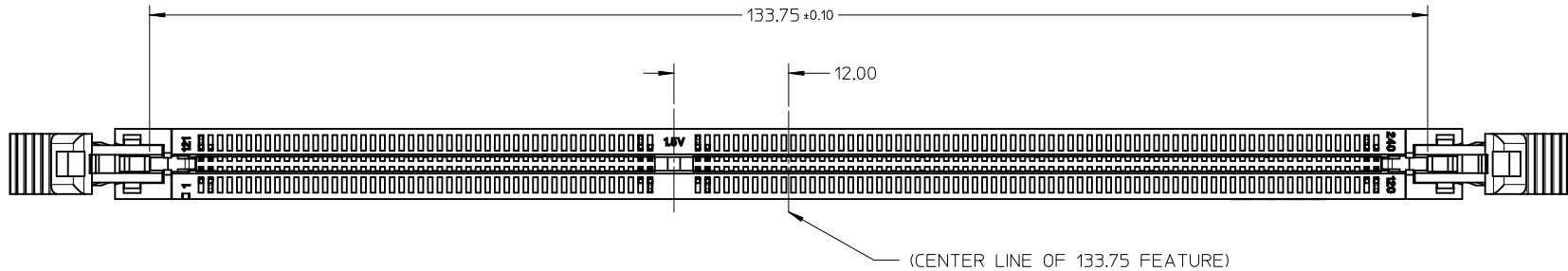


- NOTES:
- MATERIALS  
HOUSING - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, COLOUR - BLACK  
LATCH - HIGH TEMP NYLON, COLOUR - BLACK  
- POLYSULFONE, UL 94HB - CLEAR  
TERMINAL - PHOSPHOR BRONZE
  - PLATING - SEE TABLE IN SHEET 4.
  - REFER TO PRODUCT SPEC. PS-78443-001 FOR PERFORMANCE SPECIFICATIONS.
  - PRODUCT SHALL BE PACKED IN TRAY.
  - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED FROM P.C.PADS).
- 6 MODULE SEATING PLANE FROM TOP OF PCB.  
 7 KEEP OUT ZONE RESERVED FOR LATCH.  
 8 MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.

FINAL RELEASE EC NO: S2010-0504 DRW:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
		mm	INCH	DRAWN BY	DATE	TITLE		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CMTEO	2008/06/19	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR		
		2 PLACES ± 0.2 ± ---	CHECKED BY	DATE	MOLEX MOLEX INCORPORATED			
		1 PLACE ± --- ± ---	CGTAN	2008/07/25				
		ANGULAR ± 1 °	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
			CGTAN	2008/07/25	SEE TABLE	SD-78443-001	1 OF 6	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			A3					

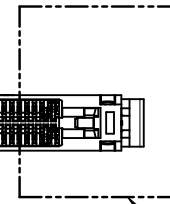
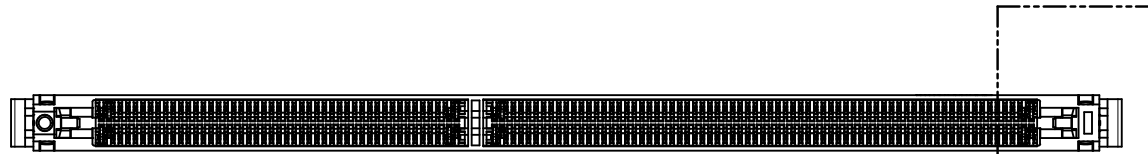
10 9 8 7 6 5 4 3 2 1



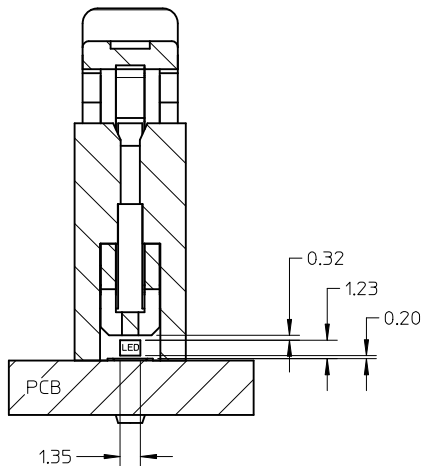
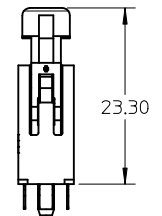
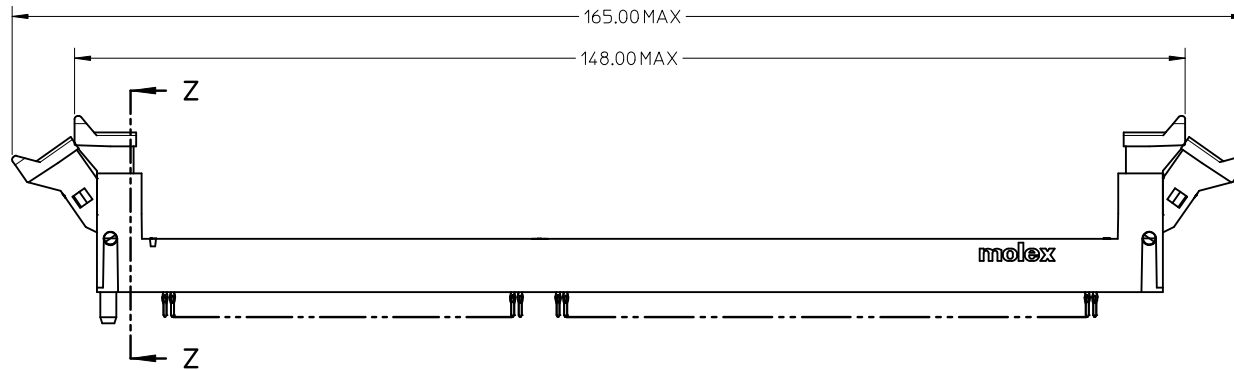
<b>FINAL RELEASE</b> EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DIMENSION STYLE <b>MM ONLY</b> DRAWN BY: CMTEO DATE: 2008/06/19 CHECKED BY: CGTAN DATE: 2008/07/25 APPROVED BY: CGTAN DATE: 2008/07/25	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE DOCUMENT NO.: SD-78443-001 SHEET NO.: 2 OF 6	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	SIZE: A3				

9 8 7 6 5 4 3 2 1

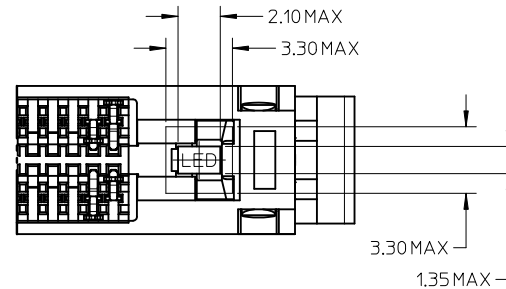
# CONNECTOR WITH CLEAR LATCH



DETAIL 2



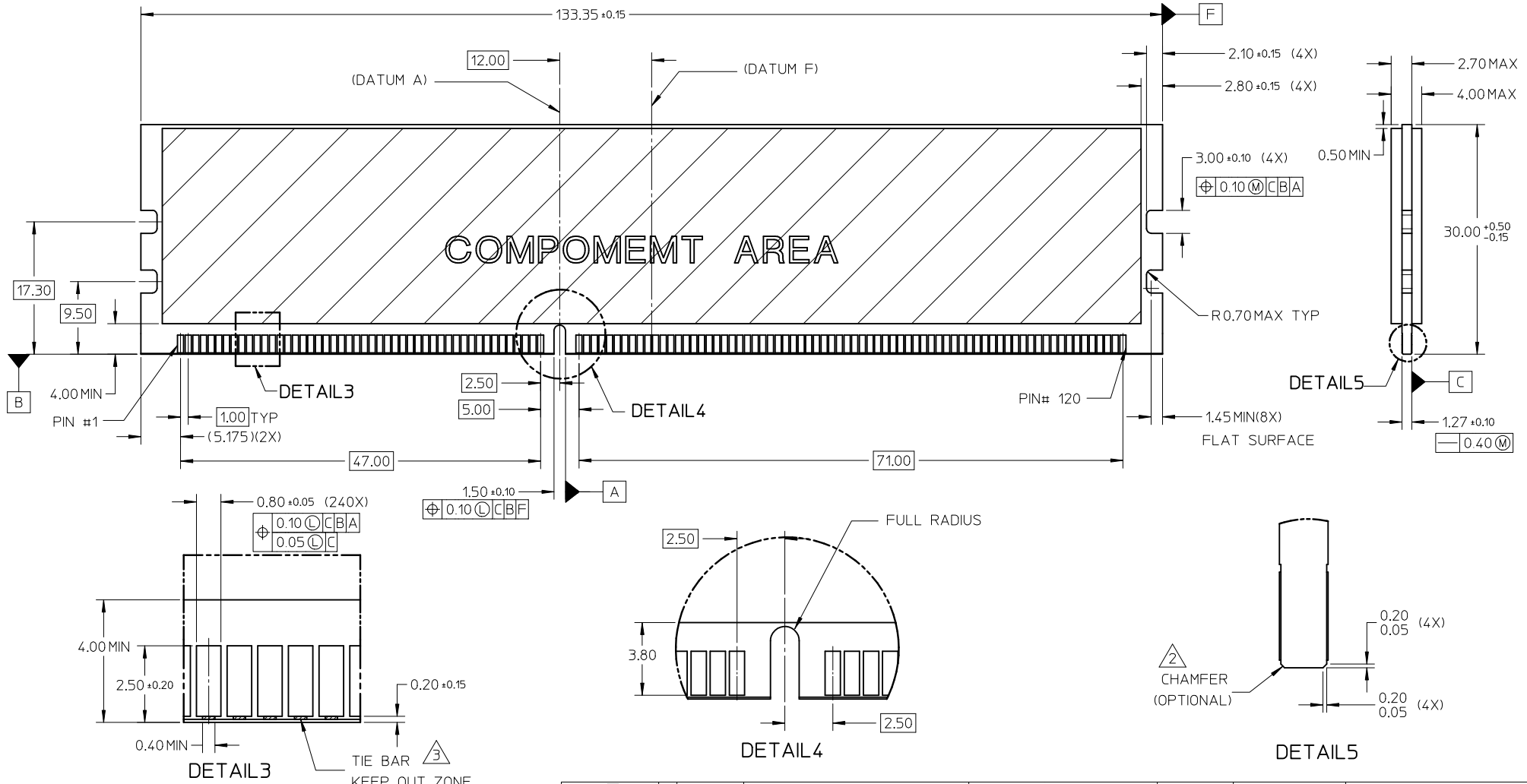
SECTION Z-Z



DETAIL 2

<b>FINAL RELEASE</b> EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES $\pm$ --- $\pm$ --- 3 PLACES $\pm$ --- $\pm$ --- 2 PLACES $\pm 0.2$ $\pm$ --- 1 PLACE $\pm$ --- $\pm$ --- ANGULAR $\pm 1^\circ$	DIMENSION STYLE <b>MM ONLY</b> DRAWN BY: CMTEO DATE: 2008/06/19 CHECKED BY: CGTAN DATE: 2008/07/25 APPROVED BY: CGTAN DATE: 2008/07/25	SCALE: NTS DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.: SEE TABLE SIZE: A3	MOLEX INCORPORATED DOCUMENT NO.: SD-78443-001	SHEET NO.: 3 OF 6	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

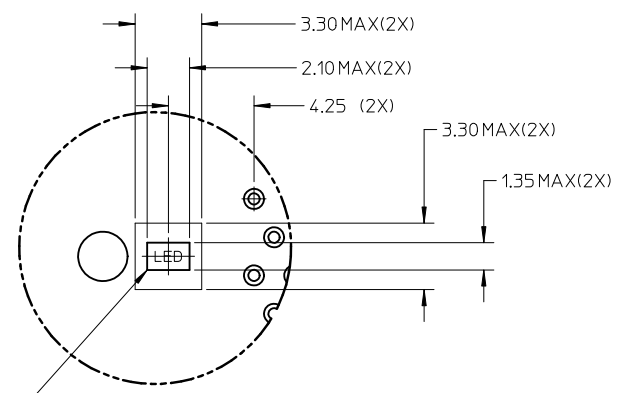
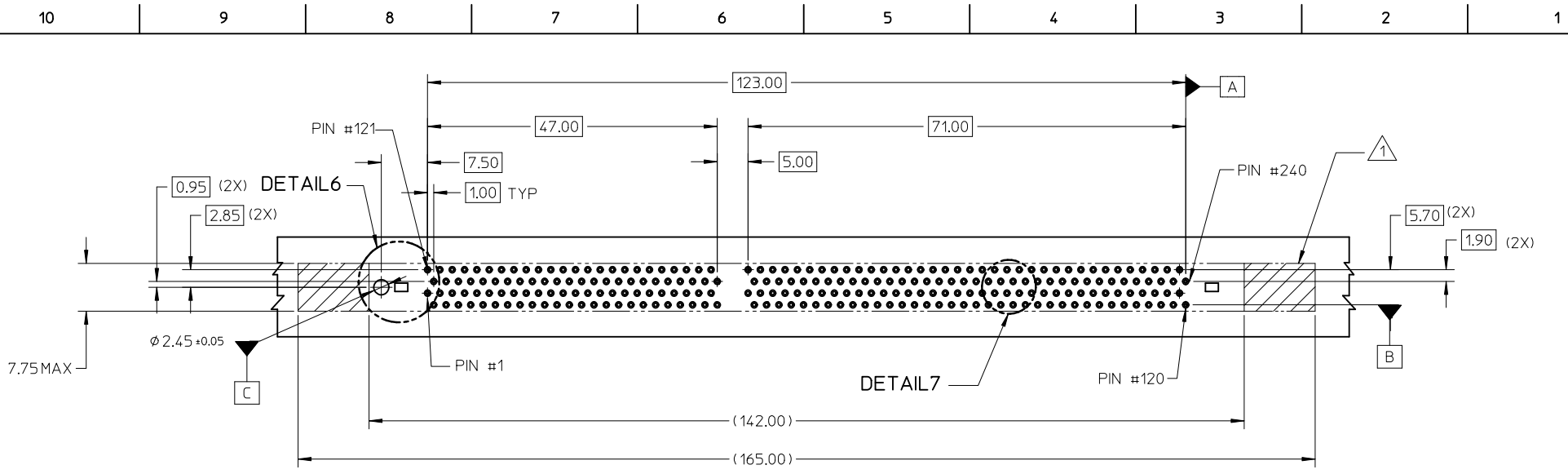
MODULE CARD  
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS  
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

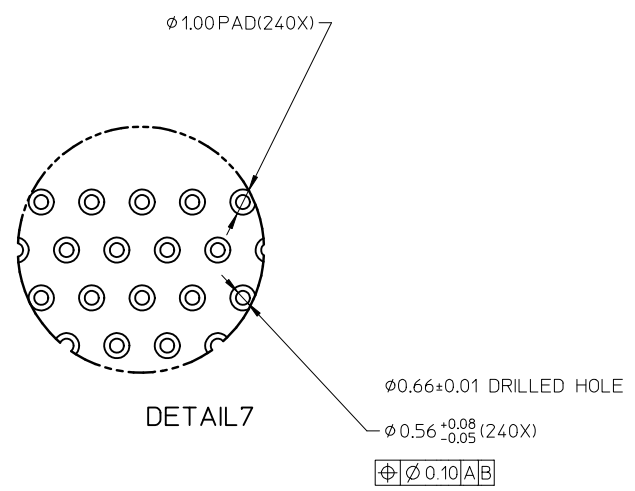
- RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN  
 OVER 2.00 MICROMETERS NICKEL  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING  
 OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC  
 CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE  
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FINAL RELEASE EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SIJENI 2009/12/31	QUALITY SYMBOLS F <sub>A</sub> =0 F <sub>E</sub> =0 F <sub>P</sub> =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC	⊕ □	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE		
		2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	CMTED	2008/06/19	DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR		
	ANGULAR ± 1 °	CHECKED BY	DATE	CGTAN	2008/07/25	MOLEX INCORPORATED		
		APPROVED BY	DATE	CGTAN	2008/07/25	DOCUMENT NO.	SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78443-001	4 OF 6	
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



DETAIL6

'LED' IS FOR CLEAR LATCH VERION ONLY



DETAIL7

NOTE:  
 1 KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

<b>FINAL RELEASE</b> EC NO: S2010-0504 DRWN:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	4 PLACES	mm	INCH	DRAWN BY CMTEO	DATE 2008/06/19	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR		
	$F_G=0$	3 PLACES	± ---	± ---	CHECKED BY CGTAN	DATE 2008/07/25	MOLEX INCORPORATED		
	$F_P=0$	2 PLACES	± 0.2	± ---	APPROVED BY CGTAN	DATE 2008/07/25	DOCUMENT NO. SD-78443-001		SHEET NO. 5 OF 6
		1 PLACE	± ---	± ---	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

TIN OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOUR
78443-0001	CENTER	1.5V	3.30±0.25	2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	0.38-1.52 MICROMETER/15-60 MICROINCH TIN OVER 1.27MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	BLACK
78443-0005			3.30±0.25	2.36			CLEAR
78443-0051			2.55±0.15	2.36			BLACK
78443-0006			2.55±0.15	2.36			CLEAR

TIN/LEAD OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOUR
78443-0011	CENTER	1.5V	3.30±0.25	2.36	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	0.38-1.52 MICROMETER/15-60 MICROINCH TIN/LEAD OVER 1.27MICROMETER/ 50 MICROINCH MIN NICKEL UNDERPLATE	BLACK
78443-0015			3.30±0.25	2.36			CLEAR
78443-0151			2.55±0.15	2.36			BLACK
78443-0016			2.55±0.15	2.36			CLEAR

<b>FINAL RELEASE</b> EC NO: S2010-0504 DRW:CGTAN 2009/12/31 CHKD:CCTEH 2009/12/31 APPR:SHLENI 2009/12/31	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla_A=0$ $\nabla_C=0$ $\nabla_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	MM ONLY	NTS	METRIC	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY DATE CMTEO 2008/06/19 CHECKED BY DATE CGTAN 2008/07/25 APPROVED BY DATE CGTAN 2008/07/25	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERT PRESS-FIT LOW-LLCR		
	REV	SIZE	MATERIAL NO.	DOCUMENT NO.		SHEET NO.
A	A3	SEE TABLE	SD-78443-001		6 OF 6	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						